

2SK302500L Datasheet



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DiGi Electronics Part Number	2SK302500L-DG
Manufacturer	Panasonic Electronic Components
Manufacturer Product Number	2SK302500L
Description	MOSFET N-CH 60V 30A U-DL
Detailed Description	N-Channel 60 V 30A (Tc) 1W (Ta), 25W (Tc) Surface Mount U-DL



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Purchase and inquiry

Manufacturer Product Number:

25K302500L

Series:

-

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

60 V

Drive Voltage (Max Rds On, Min Rds On):

4V, 10V

Vgs(th) (Max) @ Id:

2.5V @ 1mA

Input Capacitance (Ciss) (Max) @ Vds:

1200 pF @ 10 V

Power Dissipation (Max):

1W (Ta), 25W (Tc)

Mounting Type:

Surface Mount

Package / Case:

TO-252-4, DPAK (3 Leads + Tab)

Manufacturer:

Panasonic Electronic Components

Product Status:

Obsolete

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

30A (Tc)

Rds On (Max) @ Id, Vgs:

40mOhm @ 15A, 10V

Vgs (Max):

±20V

FET Feature:

-

Operating Temperature:

150°C (TJ)

Supplier Device Package:

U-DL

Environmental & Export classification

Moisture Sensitivity Level (MSL):

1 (Unlimited)

HTSUS:

8541.29.0095

ECCN:

EAR99

2SK3025

Silicon N-channel power MOS FET

■ Features

- Avalanche energy capability guaranteed
- High-speed switching
- Low ON resistance R_{on}
- No secondary breakdown
- Low-voltage drive
- High electrostatic energy capability

■ Applications

- Non-contact relay
- Solenoid drive
- Motor drive
- Control equipment
- Switching mode regulator

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V_{DSS}	60	V
Gate-source surrender voltage	V_{GSS}	± 20	V
Drain current	I_D	± 30	A
Peak drain current	I_{DP}	± 90	A
Avalanche energy capability *	EAS	45	mJ
Power dissipation	P_D	25	W
		$T_a = 25^\circ\text{C}$	1
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $L = 0.1 \text{ mH}$, $I_L = 30 \text{ A}$, 1 pulse

■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit	
Drain-source surrender voltage	V_{DSS}	$I_D = 1 \text{ mA}$, $V_{GS} = 0$	60			V	
Drain-source cutoff current	I_{DSS}	$V_{DS} = 50 \text{ V}$, $V_{GS} = 0$			10	μA	
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 20 \text{ V}$, $V_{DS} = 0$			± 10	μA	
Gate threshold voltage	V_{th}	$V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$	1.0		2.5	V	
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 10 \text{ V}$, $I_D = 15 \text{ A}$	10	18		S	
Drain-source ON resistance	$R_{DS(on)1}$	$V_{GS} = 10 \text{ V}$, $I_D = 15 \text{ A}$		25	40	m Ω	
	$R_{DS(on)2}$	$V_{GS} = 4 \text{ V}$, $I_D = 15 \text{ A}$		35	55		
Diode forward voltage	V_{DSF}	$I_{DR} = 15 \text{ A}$, $V_{GS} = 0$			-1.3	V	
Short-circuit forward transfer capacitance (Common source)	C_{iss}	$V_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 1 \text{ MHz}$		1200		pF	
					400		pF
					200		
Reverse transfer capacitance (Common source)	C_{rss}			200		pF	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 30 \text{ V}$, $I_D = 15 \text{ A}$, $R_L = 2 \Omega$ $V_{GS} = 10 \text{ V}$		10		ns	
Rise time	t_r			20		ns	
Fall time	t_f			140		ns	
Turn-off delay time	$t_{d(off)}$			350		ns	
Thermal resistance (ch-c)	$R_{th(ch-c)}$				5.0	$^\circ\text{C}/\text{W}$	
Thermal resistance (ch-a)	$R_{th(ch-a)}$				125	$^\circ\text{C}/\text{W}$	

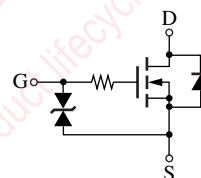
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

■ Package

- Code
U-DL
- Pin Name
1: Gate
2: Drain
3: Source

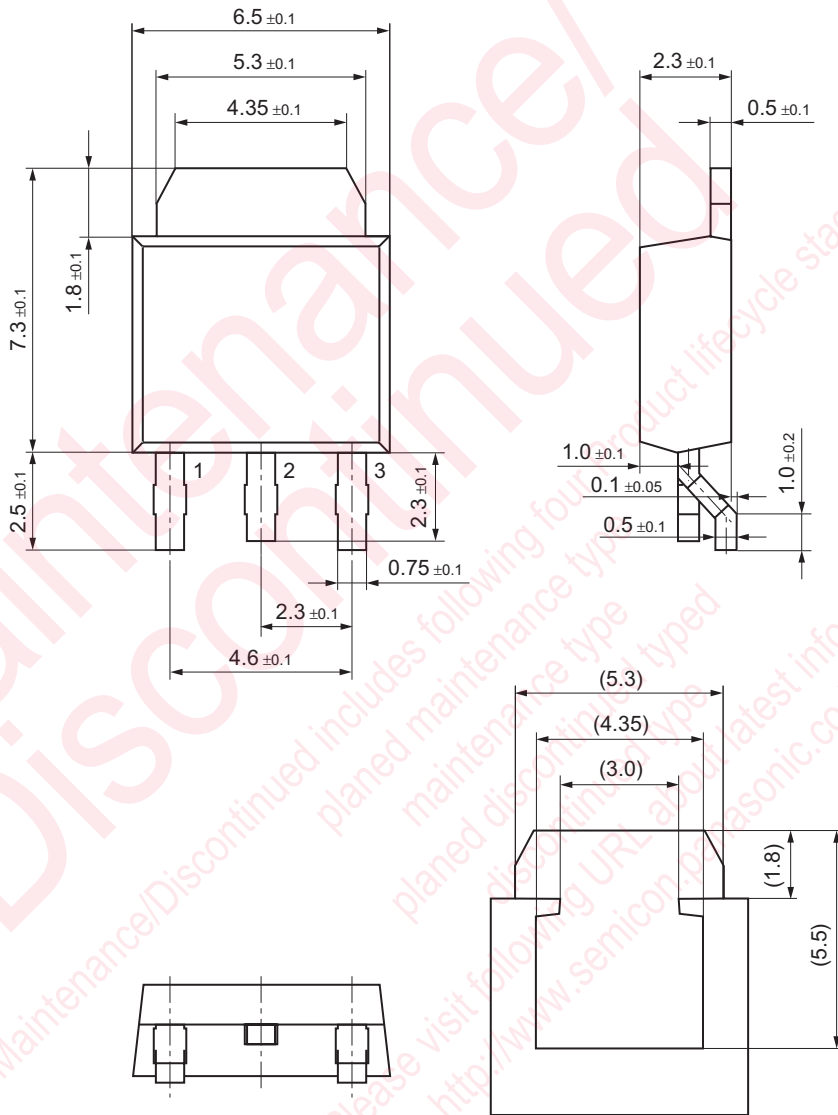
■ Marking Symbol: K3025

■ Internal Connection



U-DL

Unit: mm



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